

**1.0Amp. Surface Mount Fast Recovery Diodes**

CFR10XSF Series

Features

- For surface mounted applications.
- Plastic material used carries Underwriters Laboratory Flammability Classification 94V-0
- Low leakage current
- High surge capability
- High temperature soldering: 250°C/10 seconds at terminals
- Exceeds environmental standards of MIL-S-19500/228

Mechanical Data

- Case: Molded plastic, JEDEC SOD-123/Mini SMA.
- Terminals: Solder plated, solderable per MIL-STD-750 method 2026
- Polarity: Indicated by cathode band.
- Packaging: 12mm tape per EIA STD RS-481.
- Weight: 0.04 gram

Maximum Ratings and Electrical Characteristics

(Rating at 25°C ambient temperature unless otherwise specified.)

Parameter	Symbol	Type							Units
		CFR 101	CFR 102	CFR 103	CFR 104	CFR 105	CFR 106	CFR 107	
Repetitive peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _R	50	100	200	400	600	800	1000	V
Maximum instantaneous forward voltage, I _F =1A (Note 1)	V _F	1.3	1.3	1.3	1.3	1.3	1.3	1.3	V
Reverse Recovery Time	t _{rr}	150	150	150	150	250	500	500	ns
Average forward rectified current @T _A =55°C	I _O	1							A
Peak forward surge current @8.3ms single half sine wave superimposed on rated load (JEDEC method)	I _{FSM}	30							A
Maximum DC reverse current V _R =V _{RRM} , T _A =25°C (Note 1) V _R =V _{RRM} , T _A =100°C (Note 1)	I _R	5 100							μA μA
Maximum thermal resistance, Junction to ambient	R _{th,JA}	42 (typ)							°C/W
Diode junction capacitance (Note 2)	C _J	15 (typ)							pF
Storage temperature	T _{stg}	-55 ~ +150							°C
Operating temperature	T _J	-55 ~ +150							°C

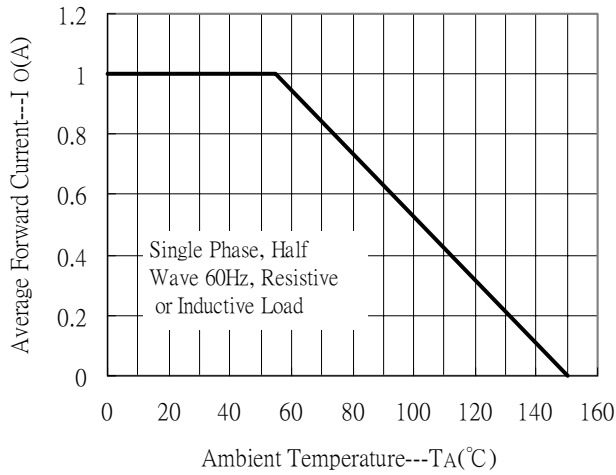
Notes : 1. Pulse test, pulse width=300 μ sec, 2% duty cycle

2. f=1MHz and applied 4.0V_{DC} reverse voltage.

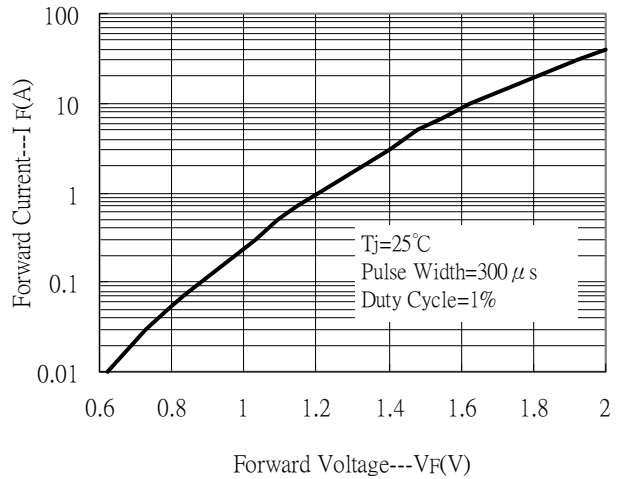


Characteristic Curves

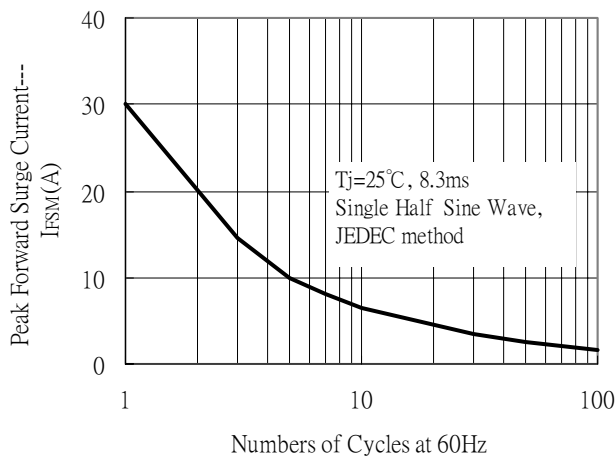
Forward Current Derating Curve



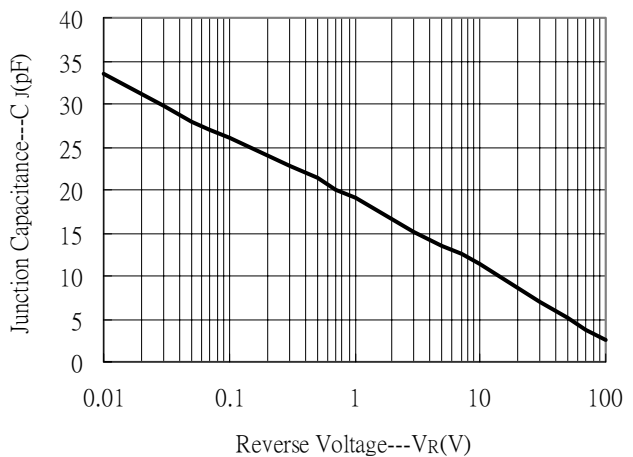
Forward Current vs Forward Voltage



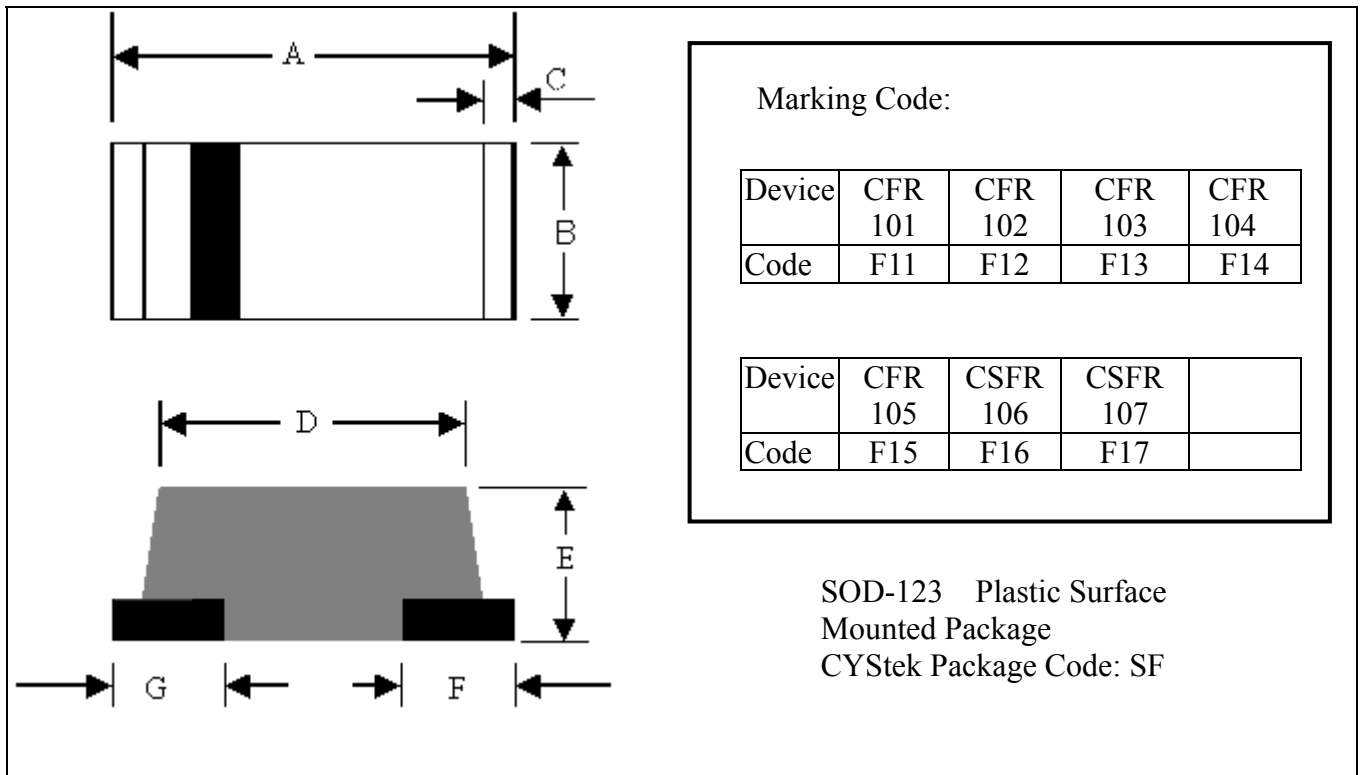
Maximum Non-Repetitive Forward Surge Current



Junction Capacitance vs Reverse Voltage



SOD-123 Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.146	0.161	3.7	4.1	E	0.055	0.063	1.4	1.6
B	0.055	0.071	1.4	1.8	F	0.035(typ)		0.9(typ)	
C	0.012(typ)		0.3(typ)		G	0.035(typ)		0.9(typ)	
D	0.094	0.110	2.4	2.8	-	-	-	-	-

Notes : 1.Controlling dimension : millimeters.

2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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